

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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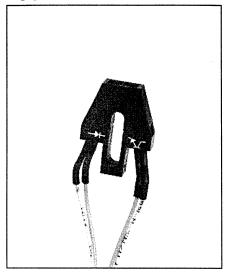


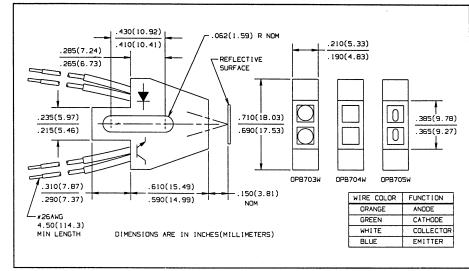






Reflective Object Sensors Types OPB703W, OPB704W, OPB705W





Features

- Phototransistor output
- · High sensitivity
- Low cost plastic housing
- Available with lenses for dust protection and ambient light filtration

Description

The OPB703W, OPB704W and OPB705W each consist of an infrared emitting diode and an NPN silicon phototransistor mounted side-by-side on converging optical axes in a black plastic housing. The phototransistor responds to radiation from the emitter only when a reflective object passes within its field of view. Various options allow no lens, blue polysulfone lens for dust protection or offset lens for improved resolution.

Leads are 26 AWG, PVC insulation, 4.5" (114.3mm) minimum length, stripped & tinned.

Absolute Maximum Ratings (T_A = 25° C unless otherwise noted)

Storage and Operating Temperature	-40° C to +80° C
Lead Soldering Temperature [1/16 inch (1.6 mm) from case for 5 sec.	with soldering
iron]	240° Č ⁽¹⁾
Input Diode	
Forward DC Current	40 mA
Reverse DC Voltage	2.0 V
Power Dissipation	100 mW ⁽²⁾
Output Phototransistor	
Collector-Emitter Voltage	30 V
Emitter-Collector Voltage	5.0 V
Collector DC Current	
Power Dissipation	100 mW ⁽²⁾
Notes	

- (1) RMA flux is recommended. Duration can be extended to 10 sec. max when flow soldering.
- (2) Derate linearly 1.82 mW/° C above 25° C.
- (3) d is the distance from the assembly face to the reflective surface.
- (4) Lower curve is based on a calculated worst case condition rather than the conventional -2σ limit
- (5) All parameters tested using pulse technique.
- (6) Crosstalk is the photocurrent measured with current to the input diode and no reflecting surface.
- (7) Measured using Eastman Kodak neutral white test card with 90% diffuse reflectance as a reflecting surface. Reference: Eastman Kodak, Catalog #1257795.

DESCRIPTION

OPB703W No Lens
OPB704W Blue Polysulfone Lens
OPB705W Offset Lens



For RoHS compliant devices add "Z" to the end of the part number: OPB703WZ

REFLECTIVE OBJECT SENSORS

Types OPB703W, OPB704W, OPB705W

Electrical Characteristics (T_A = 25° C unless otherwise noted)

SYMBOL	PARAMETER		MIN	MAX	UNITS	TEST CONDITIONS
Input Diode	<u> </u>					
	Forward Voltage			1.70	V	I _F = 40 mA
IR	Reverse Current			100	μА	V _R = 2.0 V
Output Pho	ototransistor					
V _(BR) CEO	Collector-Emitter Breakdown Voltage		30		V	I _{CE} = 100 μA
V _{(BR)ECO}	Emitter-Collector Breakdown Voltage		5.0		V	I _{EC} = 100 μA
ICEO	Collector Dark Current			100	nA	$V_{CE} = 10 \text{ V}, I_F = 0, E_e = 0$
Combined						
Ic(on)	On-State Collector Current	OPB703W OPB704W OPB705W	200 200 100		μΑ μΑ μΑ	V _{CE} = 5 V, I _F = 40 mA, d = 0.15 in. (3.81 mm) ⁽³⁾⁽⁷⁾
lcx	Crosstalk	OPB703W OPB704W OPB705W		20 20 10	μΑ μΑ μΑ	V _{CE} = 5 V, I _F = 40 mA ⁽⁶⁾

Typical Performance Curves

